

present invention;

Fig. 2A and Fig. 2B are explanatory views showing a state in which an inorganic filler in a thermosetting resin is forced outwardly of a bump due to a pointed bump that enters the thermosetting resin at the beginning of bonding by a method for mounting an electronic component of, for example, an IC chip on a circuit board according to the first embodiment, and Fig. 2C is an explanatory view of a state in which no inorganic filler enters a space between the bump and the board electrode;

Fig. 3A, Fig. 3B, Fig. 3C, Fig. 3D, Fig. 3E, Fig. 3F, and Fig. 3G are explanatory views showing a bump forming process by means of a wire bonder for an IC chip by the mounting method of the first embodiment of the present invention;

Fig. 4A, Fig. 4B and Fig. 4C are explanatory views showing a process for bonding an IC chip to a circuit board by the mounting method of the first embodiment of the present invention;

Fig. 5A, Fig. 5B and Fig. 5C are explanatory views showing a process for bonding an IC chip to a circuit board by the mounting method of the first embodiment of the present invention;

Fig. 6A, Fig. 6B and Fig. 6C are explanatory views for explaining a thermosetting adhesive arranged on a

circuit board in place of an anisotropic conductive film sheet by a mounting method according to a third embodiment of the present invention, and Fig. 6D and Fig. 6E are enlarged explanatory views of the bonded state of the first
5 embodiment;

Fig. 7A, Fig. 7B, Fig. 7C, Fig. 7D, Fig. 7E and Fig. 7F are explanatory views for explaining a thermosetting adhesive arranged on a circuit board in place of an anisotropic conductive film sheet according to a
10 modification example of Fig. 6A through Fig. 6E by the mounting method of the third embodiment of the present invention;

Fig. 8A, Fig. 8B and Fig. 8C are explanatory views showing a process for bonding an IC chip to a circuit
15 board by a mounting method according to a fifth embodiment of the present invention;

Fig. 9A, Fig. 9B and Fig. 9C are explanatory views showing a process for bonding an IC chip to a circuit board by the mounting method of the fifth embodiment of the
20 present invention;

Fig. 10A, Fig. 10B, Fig. 10C and Fig. 10D are explanatory views showing a process for bonding an IC chip to a circuit board by a mounting method according to a sixth embodiment of the present invention;

25 Fig. 11A, Fig. 11B, Fig. 11C, Fig. 11D and Fig.

11E are explanatory views showing a process for bonding an IC chip to a circuit board by the mounting method of the sixth embodiment of the present invention;

Fig. 12A, Fig. 12B, Fig. 12C and Fig. 12D are
5 explanatory views showing a process for bonding an IC chip to a circuit board by a mounting method according to a seventh embodiment of the present invention;

Fig. 13 is an explanatory view showing a process for bonding an IC chip to a circuit board by the mounting
10 method of the seventh embodiment of the present invention;

Fig. 14A and Fig. 14B are an explanatory view showing a modification example of the first embodiment in which a thermosetting resin sheet is formed on an IC chip 1 side and an explanatory view showing a modification example
15 of the first embodiment in which a thermosetting adhesive is formed on the IC chip 1 side;

Fig. 15 is a sectional view showing a conventional method for bonding an IC chip to a circuit board;

20 Fig. 16A and Fig. 16B are explanatory views showing a conventional method for bonding an IC chip to a circuit board;

Fig. 17 is a graph of a relation between a resistance value and a load in the case of a bump that has
25 an outside diameter of 80 μm in the first embodiment;